

# 10-/8-Bit, 1.25-MSPS, MICRO-POWER, MINIATURE SAR ANALOG-TO-DIGITAL CONVERTERS

### **FEATURES**

- 1.25-MHz Sample Rate Serial Device
- 10-Bit Resolution ADS7887
- 8-Bit Resolution ADS7888
- Zero Latency
- 25-MHz Serial Interface
- Supply Range: 2.35 V to 5.25 V
- Typical Power Dissipation at 1.25 MSPS:
   3.8 mW at 3-V V<sub>DD</sub>
  - 8 mw at 5-V V<sub>DD</sub>
- ±0.35 LSB INL, DNL ADS7887
- ±0.15 LSB INL, ±0.1 LSB DNL ADS7888
- 61dB SINAD, -84 dB THD ADSA7887
- 49.5 dB SINAD, -67.5 dB THD ADS7888
- Unipolar Input Range: 0 V to V<sub>DD</sub>
- Power Down Current: 1 µA
- Wide Input Bandwidth: 15 MHz at 3 dB
- 6-Pin SOT23 and SC70 Packages

## DESCRIPTION

## APPLICATIONS

- Base Band Converters in Radio Communication
- Motor Current/Bus Voltage Sensors in Digital Drives
- Optical Networking (DWDM, MEMS Based Switching)
- Optical Sensors
- Battery Powered Systems
- Medical Instrumentations
- High-Speed Data Acquisition Systems
- High-Speed Closed-Loop Systems

The ADS7887 is a 10-bit, 1.25-MSPS analog-to-digital converter (ADC), and the ADS7888 is a 8-bit, 1.25-MSPS ADC. The devices include a capacitor based SAR A/D converter with inherent sample and hold. The serial interface in each device is controlled by the  $\overline{CS}$  and SCLK signals for glueless connections with microprocessors and DSPs. The input signal is sampled with the falling edge of  $\overline{CS}$ , and SCLK is used for conversion and serial data output.

The devices operate from a wide supply range from 2.35 V to 5.25 V. The low power consumption of the devices make them suitable for battery-powered applications. The devices also include a power saving powerdown feature for when the devices are operated at lower conversion speeds.

The high level of the digital input to the device is not limited to device  $V_{DD}$ . This means the digital input can go as high as 5.25 V when device supply is 2.35 V. This feature is useful when digital signals are coming from other circuit with different supply levels. Also this relaxes restriction on power up sequencing.

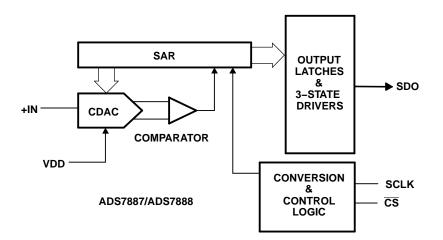
The ADS7887 and ADS7888 are available in 6-pin SOT23 and SC70 packages and are specified for operation from -40°C to 125°C.

#### **Micro-Power Miniature SAR Converter Family**

BIT	< 300 KSPS	300 KSPS – 1.25 MSPS
12-Bit	ADS7866 (1.2 $V_{\text{DD}}$ to 3.6 $V_{\text{DD}}$ )	ADS7886 (2.35 $V_{\text{DD}}$ to 5.25 $V_{\text{DD}}$ )
10-Bit	ADS7867 (1.2 $V_{\text{DD}}$ to 3.6 $V_{\text{DD}}$ )	ADS7887 (2.35 $V_{\text{DD}}$ to 5.25 $V_{\text{DD}}$ )
8-Bit	ADS7868 (1.2 V <sub>DD</sub> to 3.6 V <sub>DD</sub> )	ADS7888 (2.35 V <sub>DD</sub> to 5.25 V <sub>DD</sub> )



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

		0								
DEVICE	MAXIMUM INTEGRAL LINEARITY (LSB)	MAXIMUM DIFFEREN- TIAL LINEARITY (LSB)	NO MISSING CODES AT RESOLUTION (BIT)	PACK- AGE TYPE	PACK- AGE DESIG- NATOR	TEMPERATURE RANGE	PACKAGE MARKING	ORDERING INFORMATION	TRANSPORT MEDIA QUANTITY	
				6-Pin	DBV		BAWQ	ADS7887SDBVT	Tape and reel 250	
ADS7887	+0.75	10.5	10	SOT23	SOT23	DBV	–40°C to 125°C	BAWQ	ADS7887SDBVR	Tape and reel 3000
AD37007	±0.75 ±0.5	±0.5		6-Pin		40°C 10 125°C	BNI	ADS7887SDCKT	Tape and reel 250	
				SC70			BNI	ADS7887SDCKR	Tape and reel 3000	
		10.0		6-Pin	DBV		BAZQ	ADS7888SDBVT	Tape and reel 250	
ADS7888	±0.3		8	SOT23	DBV	–40°C to 125°C	BAZQ	ADS7888SDBVR	Tape and reel 3000	
AD31000	10.3	±0.3	8	6-Pin SC70	DCK	-40 C 10 123 C	BNH	ADS7888SDCKT	Tape and reel 250	
					DCK		BNH	ADS7888SDCKR	Tape and reel 3000	

#### PACKAGE/ORDERING INFORMATION<sup>(1)</sup>

(1) For most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

#### **ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

		UNIT
+IN to AGND		-0.3 V to +V <sub>DD</sub> +0.3 V
+V <sub>DD</sub> to AGND		–0.3 V to 7.0 V
Digital input voltage to GND		-0.3V to (7.0 V)
Digital output to GND	–0.3 V to (+V <sub>DD</sub> + 0.3 V)	
Operating temperature range		–40°C to 125°C
Storage temperature range		–65°C to 150°C
Junction temperature (T <sub>J</sub> Max)		150°C
Power dissipation, SOT23 and SO	C70 packages	$(T_J Max - T_A)/\theta_{JA}$
0 Thormal impadance	SOT23	295.2°C/W
$\theta_{JA}$ Thermal impedance	SC70	351.3°C/W
Lood tomporature, coldering	Vapor phase (60 sec)	215°C
Lead temperature, soldering	Infrared (15 sec)	220°C

(1) Stresses above those listed under *absolute maximum ratings* may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

## **ADS7887 SPECIFICATIONS**

+V\_{DD} = 2.35 V to 5.25 V, T\_A = -40°C to 125°C,  $\rm f_{sample}$  = 1.25 MHz

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALO	G INPUT		1			
	Full-scale input voltage span <sup>(1)</sup>		0		$V_{DD}$	V
	Absolute input voltage range	+IN	-0.20		V <sub>DD</sub> +0.20	V
Ci	Input capacitance <sup>(2)</sup>			21		pF
l <sub>llkg</sub>	Input leakage current	$T_A = 125^{\circ}C$		40		nA
SYSTEM	M PERFORMANCE					
	Resolution			10		Bits
	No missing codes		10			Bits
INL	Integral nonlinearity		-0.75	±0.35	0.75	LSB <sup>(3</sup>
DNL	Differential nonlinearity		-0.5	±0.35	0.5	LSB
Eo	Offset error <sup>(4)(5)(6)</sup>		-1.5	±0.5	1.5	LSB
E <sub>G</sub>	Gain error <sup>(5)</sup>		-1	±0.5	1	LSB
SAMPL	ING DYNAMICS					
	Conversion time	25-MHz SCLK	530	560		ns
	Acquisition time		260			ns
	Maximum throughput rate	25-MHz SCLK			1.25	MHz
	Aperture delay			5		ns
	Step Response			160		ns
	Overvoltage recovery			160		ns
DYNAM	IC CHARACTERISTICS					
THD	Total harmonic distortion <sup>(7)</sup>	100 kHz		-84	-72	dB
SINAD	Signal-to-noise and distortion	100 kHz	60.5	61		dB
SFDR	Spurious free dynamic range	100 kHz	73	81		dB
	Full power bandwidth	At –3 dB		15		MHz
DIGITAI						
Logic fa	mily — CMOS					
V <sub>IH</sub>	High-level input voltage	VDD = 2.35 V to 5.25 V	V <sub>DD</sub> - 0.4		5.25	V
		$V_{DD} = 5 V$			0.8	
V <sub>IL</sub>	Low-level input voltage	V <sub>DD</sub> = 3 V			0.4	V
V <sub>OH</sub>	High-level output voltage	At I <sub>source</sub> = 200 µA	V <sub>DD</sub> -0.2			
V <sub>OL</sub>	Low-level output voltage	At $I_{sink} = 200 \ \mu A$	00		0.4	V
	SUPPLY REQUIREMENTS	onny .	<u> </u>			
+V <sub>DD</sub>	Supply voltage		2.35	3.3	5.25	V
00		At V <sub>DD</sub> = 2.35 V to 5.25 V, 1.25-MHz throughput			2	
	Supply current (normal mode)	At $V_{DD}$ = 2.35 V to 5.25 V, static state			1.5	mA
		SCLK off			1	
	Power down state supply current	SCLK on (25 MHz)			200	μA
	Dowor dissipation at 1.25 MU-	$V_{DD} = 5 V$		8	10	
	Power dissipation at 1.25 MHz throughput	· uu · ·		0	.0	mW

Ideal input span; does not include gain or offset error.
 Refer Figure 36 for details on sampling circuit

(3) LSB means least significant bit

(4) Measured relative to an ideal full-scale input
(5) Offset error and gain error ensured by characterization.

(6) (7)

First transition of 000H to 001H at 0.5 ×  $(V_{ref}/2^{10})$ Calculated on the first nine harmonics of the input frequency

# ADS7887 SPECIFICATIONS (continued)

+V<sub>DD</sub> = 2.35 V to 5.25 V, T<sub>A</sub> = -40°C to 125°C, f<sub>sample</sub> = 1.25 MHz

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
Dower dissipation in static state	$V_{DD} = 5 V$		5.5	7.5	m\//	
Power dissipation in static state	V <sub>DD</sub> = 3 V		3	4.5	mW	
Power down time				0.1	μs	
Power up time				0.8	μs	
Invalid conversions after power up				1		
TEMPERATURE RANGE						
Specified performance		-40		125	°C	

#### **ADS7888 SPECIFICATIONS**

+V\_{DD} = 2.35 V to 5.25 V, T\_A = -40°C to 125°C,  $\rm f_{sample}$  = 1.25 MHz

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALO	G INPUT					
	Full-scale input voltage span <sup>(1)</sup>		0		$V_{DD}$	V
	Absolute input voltage range	+IN	-0.20		V <sub>DD</sub> +0.20	V
Ci	Input capacitance <sup>(2)</sup>			21		pF
l <sub>likg</sub>	Input leakage current	$T_A = 125^{\circ}C$		40		nA
SYSTE	M PERFORMANCE					
	Resolution			8		Bits
	No missing codes		8			Bits
INL	Integral nonlinearity		-0.3	±0.15	0.3	LSB <sup>(3)</sup>
DNL	Differential nonlinearity		-0.3	±0.1	0.3	LSB
Eo	Offset error <sup>(4)(5)(6)</sup>		-0.5	±0.15	0.5	LSB
E <sub>G</sub>	Gain error <sup>(5)</sup>		-0.5	±0.15	0.5	LSB
	ING DYNAMICS	· · · · · · · · · · · · · · · · · · ·				
	Conversion time	25-MHz SCLK	450	480		ns
	Acquisition time	1.5 MSPS mode, Figure 3	206			ns
	Maximum throughput rate	25-MHz SCLK			1.25	MHz
	Aperture delay			5		ns
	Step Response			160		ns
	Overvoltage recovery			160		ns
DYNAM	IIC CHARACTERISTICS		l			
THD	Total harmonic distortion <sup>(7)</sup>	100 kHz		-67.5	-65	dB
SINAD	Signal-to-noise and distortion	100 kHz	49	49.5		dB
SFDR	Spurious free dynamic range	100 kHz	65	77		dB
	Full power bandwidth	At –3 dB		15		MHz
DIGITA	L INPUT/OUTPUT		l			
Logic fa	mily — CMOS					
V <sub>IH</sub>	High-level input voltage	V <sub>DD</sub> = 2.35 V to 5.25 V	V <sub>DD</sub> -0.4		5.25	V
		$V_{DD} = 5 V$			0.8	
V <sub>IL</sub>	Low-level input voltage	V <sub>DD</sub> = 3 V			0.4	V
V <sub>OH</sub>	High-level output voltage	At I <sub>source</sub> = 200 µA	V <sub>DD</sub> -0.2			
V <sub>OL</sub>	Low-level output voltage	At $I_{sink} = 200 \ \mu A$			0.4	V
	R SUPPLY REQUIREMENTS		1			
+V <sub>DD</sub>	Supply voltage		2.35	3.3	5.25	V
	Supply current (normal mode)	At $V_{DD}$ = 2.35 V to 5.25 V, 1.25-MHz throughput			2	mA
		At $V_{DD}$ = 2.35 V to 5.25 V, static state			1.5	
		SCLK off			1	
	Power down state supply current	SCLK on (25 MHz)			200	μA
	Power dissipation at 1.25 MHz	$V_{DD} = 5 V$		8	10	
	throughput	$V_{DD} = 3 V$		3.8	6	mW

Ideal input span; does not include gain or offset error.
 Refer Figure 36 for details on sampling circuit

- (3) LSB means least significant bit

(4) Measured relative to an ideal full-scale input
(5) Offset error and gain error ensured by characterization.
(6) First transition of 000H to 001H at (V<sub>ref</sub>/2<sup>8</sup>)
(7) Calculated on the first nine harmonics of the input frequency

# **ADS7888 SPECIFICATIONS (continued)**

+V\_{DD} = 2.35 V to 5.25 V, T\_A = -40°C to 125°C,  $\rm f_{sample}$  = 1.25 MHz

•						
TEST CONDITIONS	MIN	TYP	MAX	UNIT		
$V_{DD} = 5 V$		5.5	7.5	m\//		
$V_{DD} = 3 V$		3	4.5	mW		
			0.1	μs		
			0.8	μs		
			1			
TEMPERATURE RANGE						
	-40		125	°C		
	V <sub>DD</sub> = 5 V	V <sub>DD</sub> = 5 V V <sub>DD</sub> = 3 V	V <sub>DD</sub> = 5 V 5.5 V <sub>DD</sub> = 3 V 3	$V_{DD} = 5 V$ 5.5         7.5 $V_{DD} = 3 V$ 3         4.5           0.1         0.1         0.8           1         1         1		

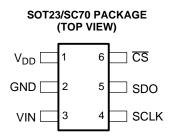
# TIMING REQUIREMENTS (see Figure 1)

All specifications typical at  $T_A = -40^{\circ}C$  to  $125^{\circ}C$ ,  $V_{DD} = 2.35$  V to 5.25 V, unless otherwise specified.

	PARAMETER		TEST CONDITIONS <sup>(1)</sup>	MIN	TYP	MAX	UNIT		
		ADS7887	$V_{DD} = 3 V$			$14  imes t_{SCLK}$			
conv	Companying time	AD57887	V <sub>DD</sub> = 5 V			$14  imes t_{SCLK}$			
t <sub>conv</sub>	Conversion time	4067000	$V_{DD} = 3 V$			$12  imes t_{SCLK}$	ns		
		ADS7888	$V_{DD} = 5V$			$12  imes t_{SCLK}$			
	Minimum quiet time needed from t	ous 3-state to start	V <sub>DD</sub> = 3 V	40					
t <sub>q</sub>	of next conversion		$V_{DD} = 5 V$	40			ns		
		t	V <sub>DD</sub> = 3 V		15	25			
t <sub>d1</sub>	Delay time, $\overline{CS}$ low to first data (0)	out	V <sub>DD</sub> = 5 V		13	25	ns		
			V <sub>DD</sub> = 3 V	10			ns		
t <sub>su1</sub>	Setup time, $\overline{CS}$ low to SCLK low		V <sub>DD</sub> = 5 V	10					
		$V_{DD} = 3 V$		15	25				
t <sub>d2</sub>	Delay time, SCLK falling to SDO		$V_{DD} = 5 V$		13	25	ns		
		: 1(2)	V <sub>DD</sub> < 3 V	7					
t <sub>h1</sub>	Hold time, SCLK falling to data val	IQ (2)	V <sub>DD</sub> > 5 V	5.5			ns		
t <sub>d3</sub> De			$V_{DD} = 3 V$		10	25			
	Delay time, 16th SCLK falling edge	e to SDO 3-state	$V_{DD} = 5 V$		8	20	ns		
	Dulas duration <u>CC</u>		V <sub>DD</sub> = 3 V	25	40		1		
t <sub>w1</sub>	Pulse duration, CS		$V_{DD} = 5 V$	25	40		ns		
			$V_{DD} = 3 V$		17	30	ns		
t <sub>d4</sub>	Delay time, CS high to SDO 3-stat	e, Figure 3	V <sub>DD</sub> = 5 V		15	25			
	Delas destina 2014/histo		$V_{DD} = 3 V$	$0.4  imes t_{SCLK}$					
t <sub>wH</sub>	Pulse duration, SCLK high		V <sub>DD</sub> = 5 V	$0.4  imes t_{SCLK}$			ns		
	Dulas duration, CCLK low		$V_{DD} = 3 V$	$0.4  imes t_{SCLK}$			5		
t <sub>wL</sub>	Pulse duration, SCLK low		$V_{DD} = 5 V$	$0.4  imes t_{SCLK}$			ns		
			$V_{DD} = 3 V$			25			
	Frequency, SCLK		$V_{DD} = 5 V$			25	MHz		
	Delay time, second falling edge of		V <sub>DD</sub> = 3 V	-2		5			
t <sub>d5</sub>	enter in powerdown (use min spec enter in powerdown) Figure 4	not to accidently	V <sub>DD</sub> = 5 V	-2		5	ns		
	Delay time, $\overline{CS}$ and 10th falling ed		$V_{DD} = 3 V$	2		-5			
t <sub>d6</sub>	enter in powerdown (use max specenter in powerdown) Figure 4	c not to accidently	V <sub>DD</sub> = 5 V	2		-5	ns		

3-V Specifications apply from 2.35 V to 3.6 V, and 5-V specifications apply from 4.75 V to 5.25 V.
 With 50-pf load.

#### **DEVICE INFORMATION**



#### **TERMINAL FUNCTIONS**

TERMINAL		<b>//O</b>	DESCRIPTION					
NAME	NO.	1/0	DESCRIPTION					
V <sub>DD</sub>	1	-	Power supply input also acts like a reference voltage to ADC.					
GND	2	-	Ground for power supply, all analog and digital signals are referred with respect to this pin.					
VIN	3	I	Analog signal input					
SCLK	4	I	Serial clock					
SDO	5	0	Serial data out					
CS	6	I	Chip select signal, active low					

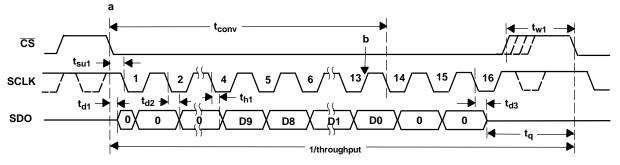
#### ADS7887 NORMAL OPERATION

The cycle begins with the falling edge of  $\overline{CS}$ . This point is indicated as **a** in Figure 1. With the falling edge of  $\overline{CS}$ , the input signal is sampled and the conversion process is initiated. The device outputs data while the conversion is in progress. The data word contains 4 leading zeros, followed by 10-bit data in MSB first format and padded by 2 lagging zeros.

The falling edge of  $\overline{CS}$  clocks out the first zero, and a zero is clocked out on every falling edge of the clock until the third edge. Data is in MSB first format with the MSB being clocked out on the 4th falling edge. Data is padded with two lagging zeros as shown in Figure 1. On the 16th falling edge of SCLK, SDO goes to the 3-state condition. The conversion ends on the 14th falling edge of SCLK. The device enters the acquisition phase on the first rising edge of SCLK after the 13th falling edge. This point is indicated by **b** in Figure 1.

 $\overline{CS}$  can be asserted (pulled high) after 16 clocks have elapsed. It is necessary not to start the next conversion by pulling  $\overline{CS}$  low until the end of the quiet time (t<sub>q</sub>) after SDO goes to 3-state. To continue normal operation, it is necessary that  $\overline{CS}$  is not pulled high until point **b**. Without this, the device does not enter the acquisition phase and no valid data is available in the next cycle. (Also refer to power down mode for more details.)  $\overline{CS}$  going high any time after the conversion start aborts the ongoing conversion and SDO goes to 3-state.

The high level of the digital input to the device is not limited to device  $V_{DD}$ . This means the digital input can go as high as 5.25 V when the device supply is 2.35 V. This feature is useful when digital signals are coming from another circuit with different supply levels. Also, this relaxes the restriction on power up sequencing. However, the digital output levels ( $V_{OH}$  and  $V_{OL}$ ) are governed by  $V_{DD}$  as listed in the SPECIFICATIONS table.





## **ADS7888 NORMAL OPERATION**

The cycle begins with the falling edge of  $\overline{CS}$ . This point is indicated as **a** in Figure 2. With the falling edge of  $\overline{CS}$ , the input signal is sampled and the conversion process is initiated. The device outputs data while the conversion is in progress. The data word contains 4 leading zeros, followed by 8-bit data in MSB first format and padded by 4 lagging zeros.

The falling edge of  $\overline{CS}$  clocks out the first zero, and a zero is clocked out on every falling edge of the clock until the third edge. Data is in MSB first format with the MSB being clocked out on the 4th falling edge. Data is padded with four lagging zeros as shown in Figure 2. On the 16th falling edge of SCLK, SDO goes to the 3-state condition. The conversion ends on the 12th falling edge of SCLK. The device enters the acquisition phase on the first rising edge of SCLK after the 11th falling edge. This point is indicated by **b** in Figure 2.

 $\overline{CS}$  can be asserted (pulled high) after 16 clocks have elapsed. It is necessary not to start the next conversion by pulling  $\overline{CS}$  low until the end of the quiet time (t<sub>q</sub>) after SDO goes to 3-state. To continue normal operation, it is necessary that  $\overline{CS}$  is not pulled high until point **b**. Without this, the device does not enter the acquisition phase and no valid data is available in the next cycle. (Also refer to power down mode for more details.)  $\overline{CS}$  going high any time after the conversion start aborts the ongoing conversion and SDO goes to 3-state.

The high level of the digital input to the device is not limited to device  $V_{DD}$ . This means the digital input can go as high as 5.25 V when the device supply is 2.35 V. This feature is useful when digital signals are coming from another circuit with different supply levels. Also, this relaxes the restriction on power up sequencing. However, the digital output levels ( $V_{OH}$  and  $V_{OL}$ ) are governed by  $V_{DD}$  as listed in the SPECIFICATIONS section.

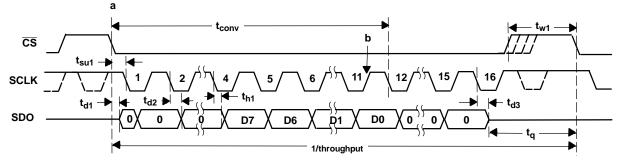


Figure 2. ADS7888 Interface Timing Diagram

As shown in Figure 3, the ADS7888 can achieve 1.5-MSPS throughput.  $\overline{CS}$  can be pulled high after the 12th falling edge (with a 25-MHz SCLK). SDO goes to 3-state after the LSB (as  $\overline{CS}$  is high).  $\overline{CS}$  can be pulled low at the end of the quiet time (t<sub>a</sub>) after SDO goes to 3-state.

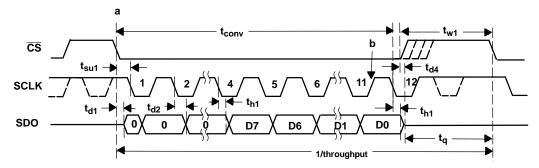


Figure 3. ADS7888 Interface Timing Diagram, Data Transfer with 12-Clock Frame

## POWER DOWN MODE

The device enters power down mode if  $\overline{CS}$  goes high anytime after the 2nd SCLK falling edge to before the 10th SCLK falling edge. Ongoing conversion stops and SDO goes to 3-state under this power down condition as shown in Figure 4.

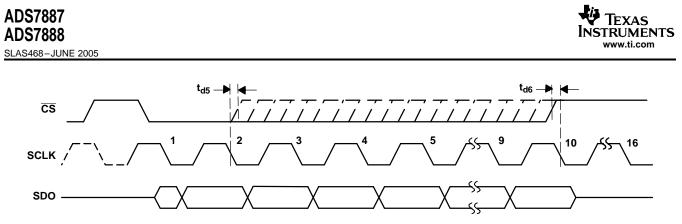


Figure 4. Entering Power Down Mode

A dummy cycle with  $\overline{CS}$  low for more than 10 SCLK falling edges brings the device out of power down mode. For the device to come to the fully powered up condition it takes 0.8 µs.  $\overline{CS}$  can be pulled high any time after the 10th falling edge as shown in Figure 5. It is not necessary to continue until the 16th clock if the next conversion starts 0.8 µs after  $\overline{CS}$  going low of the dummy cycle and the quiet time (t<sub>a</sub>) condition is met.

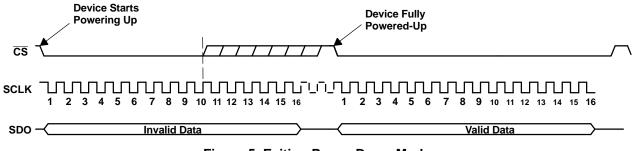
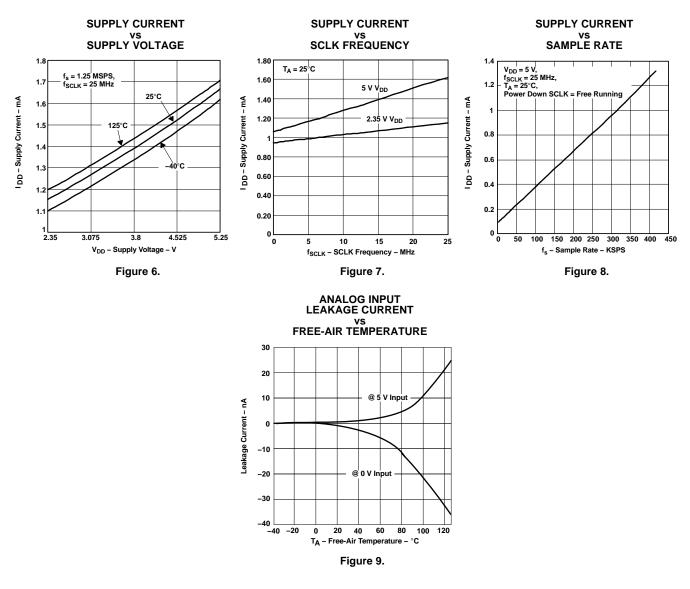


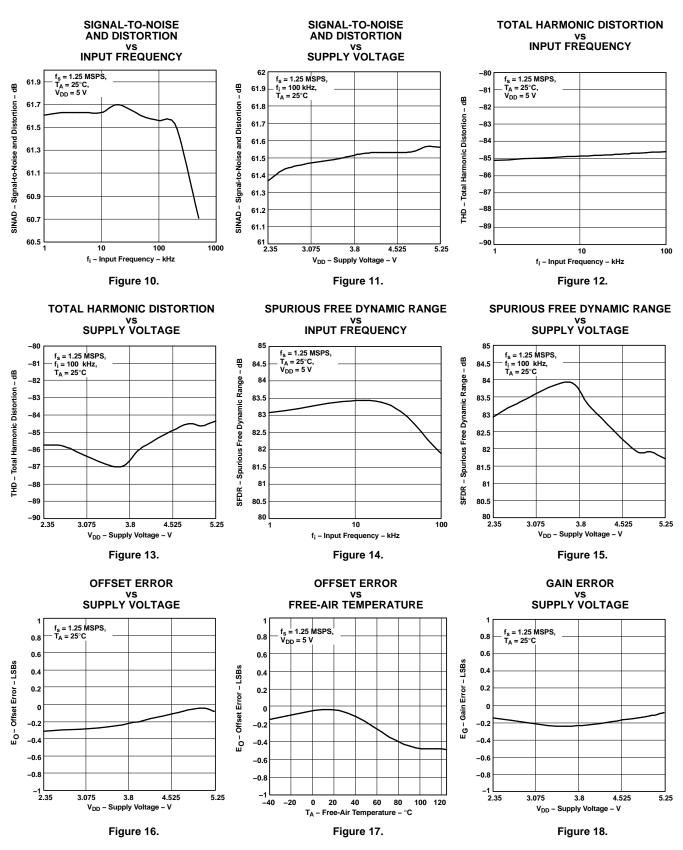
Figure 5. Exiting Power Down Mode

#### **TYPICAL CHARACTERISTICS ADS7887, ADS7888**

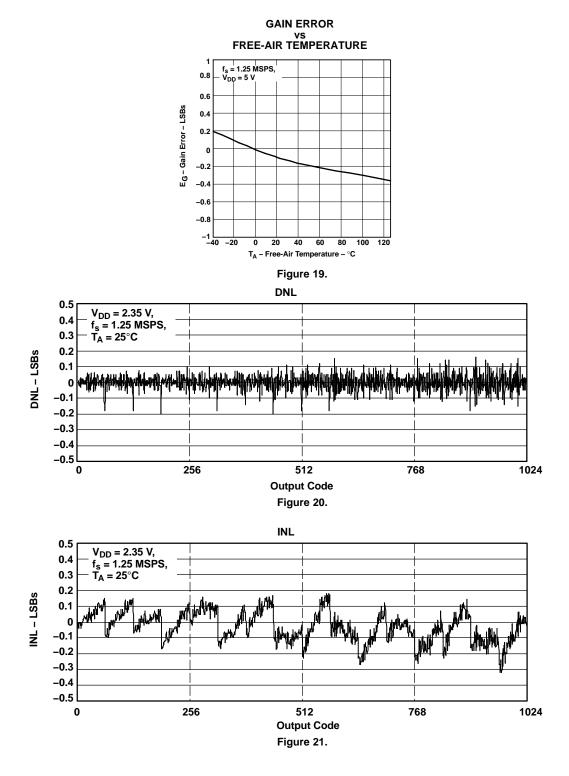




#### **TYPICAL CHARACTERISTICS ADS7887**

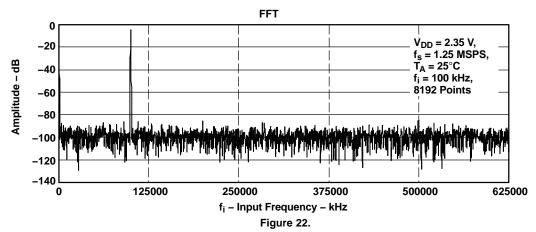


## **TYPICAL CHARACTERISTICS ADS7887 (continued)**

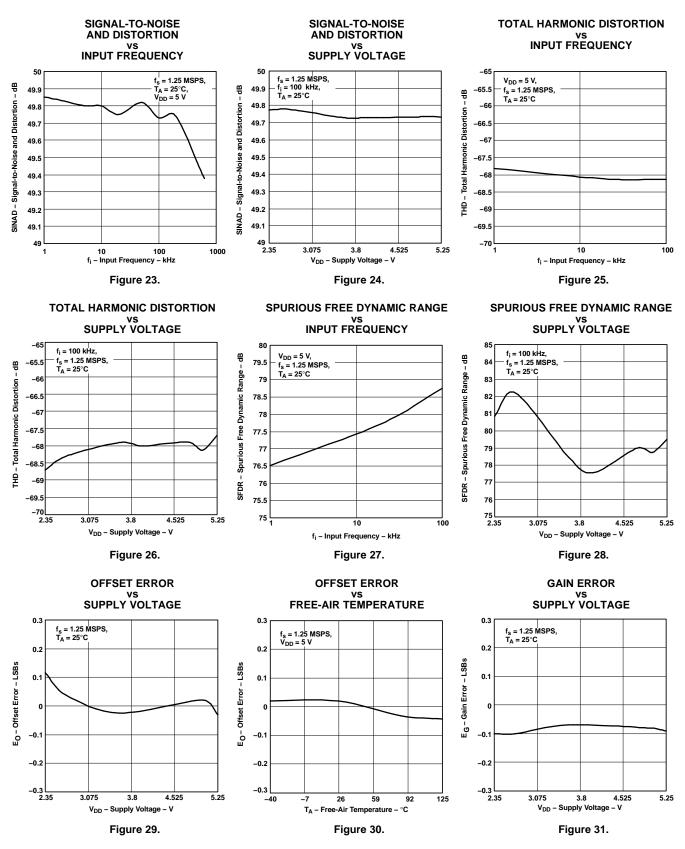


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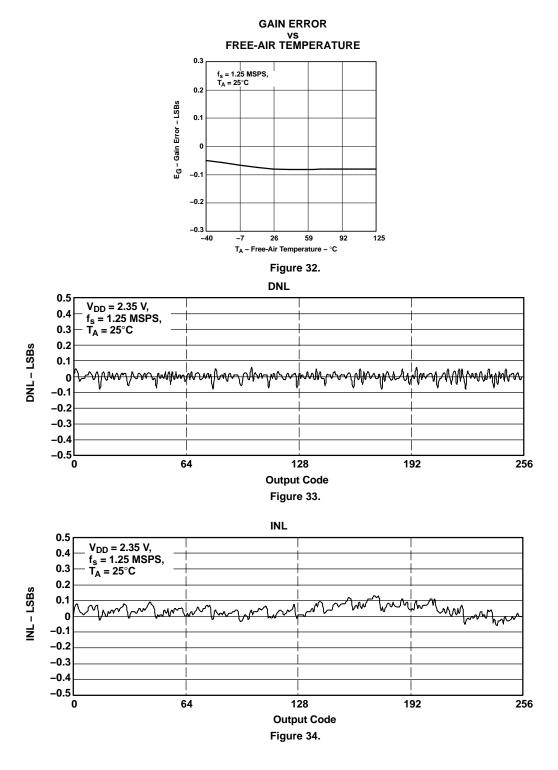
## **TYPICAL CHARACTERISTICS ADS7887 (continued)**



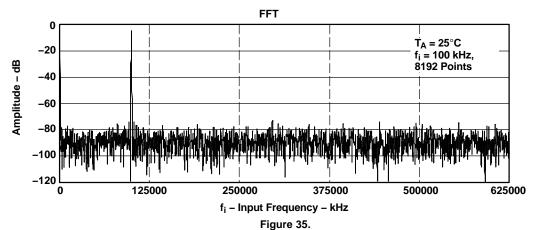
#### **TYPICAL CHARACTERISTICS ADS7888**



## **TYPICAL CHARACTERISTICS ADS7888 (continued)**



# **TYPICAL CHARACTERISTICS ADS7888 (continued)**





#### **APPLICATION INFORMATION**

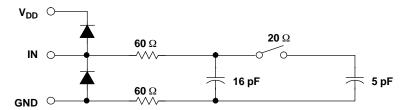


Figure 36. Typical Equivalent Sampling Circuit

#### Driving the VIN and $V_{DD}$ Pins of the ADS7887 and ADS7888

The VIN input to the ADS7887 and ADS7888 should be driven with a low impedance source. In most cases additional buffers are not required. In cases where the source impedance exceeds 200  $\Omega$ , using a buffer would help achieve the rated performance of the converter. The THS4031 is a good choice for the driver amplifier buffer.

The reference voltage for the ADS7887 and ADS7888 A/D converters are derived from the supply voltage internally. The devices offer limited low-pass filtering functionality on-chip. The supply to these converters should be driven with a low impedance source and should be decoupled to the ground. A 1- $\mu$ F storage capacitor and a 10-nF decoupling capacitor should be placed close to the device. Wide, low impedance traces should be used to connect the capacitor to the pins of the device. The ADS7887 and ADS7888 draw very little current from the supply lines. The supply line can be driven by either:

- Directly from the system supply.
- A reference output from a low drift and low drop out reference voltage generator like REF3030 or REF3130. The ADS7887 and ADS7888 can operate off a wide range of supply voltages. The actual choice of the reference voltage generator would depend upon the system. Figure 38 shows one possible application circuit.
- A low-pass filtered version of the system supply followed by a buffer like the zero-drift OPA735 can also be used in cases where the system power supply is noisy. Care should be taken to ensure that the voltage at the V<sub>DD</sub> input does not exceed 7 V (especially during power up) to avoid damage to the converter. This can be done easily using single supply CMOS amplifiers like the OPA735. Figure 39 shows one possible application circuit.

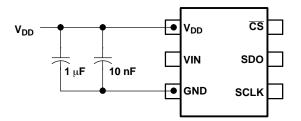


Figure 37. Supply/Reference Decoupling Capacitors

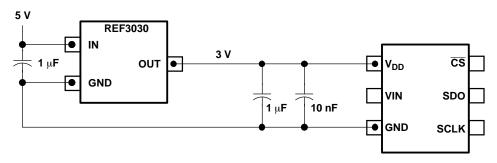


Figure 38. Using the REF3030 Reference

# **APPLICATION INFORMATION (continued)**

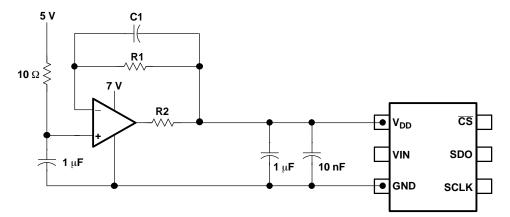


Figure 39. Buffering with the OPA735

### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
ADS7887SDBVR	ACTIVE	SOT-23	DBV	6	3000	TBD	Call TI	Call TI
ADS7887SDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM
ADS7887SDBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM
ADS7887SDCKR	ACTIVE	SC70	DCK	6	3000	TBD	Call TI	Call TI
ADS7887SDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR
ADS7887SDCKTG4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR
ADS7888SDBVR	ACTIVE	SOT-23	DBV	6	3000	TBD	Call TI	Call TI
ADS7888SDBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM
ADS7888SDBVTG4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM
ADS7888SDCKR	ACTIVE	SC70	DCK	6	3000	TBD	Call TI	Call TI
ADS7888SDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR
ADS7888SDCKTG4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	Call TI	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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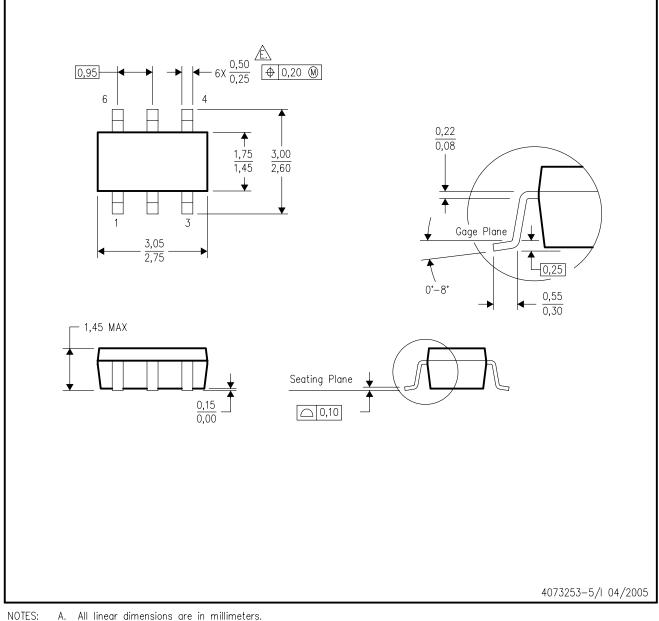
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- Α. All linear dimensions are in millimeters. Β.
- This drawing is subject to change without notice. Body dimensions do not include mold flash or protrusion.
- C. D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- E Falls within JEDEC MO-178 Variation AB, except minimum lead width.

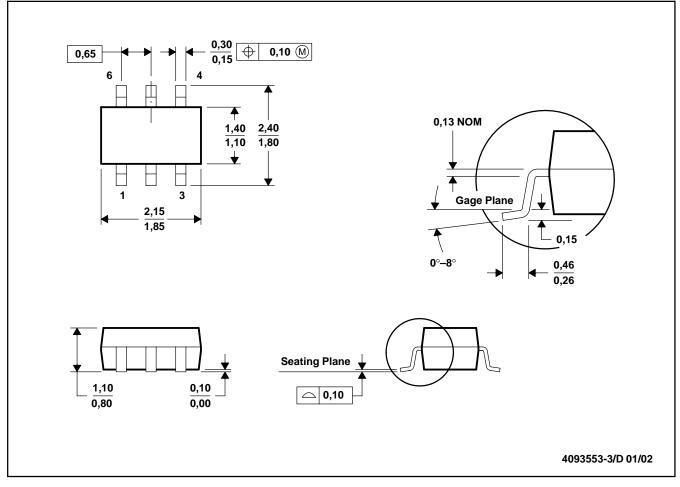


# **MECHANICAL DATA**

MPDS114 - FEBRUARY 2002

## DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-203



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